Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Straight Lead Version in Plastic Sleeves ("1" Suffix)
- Lead Formed Version in 16 mm Tape and Reel ("T4" Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Epoxy Meets UL 94, V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector–Emitter Voltage MJD31, MJD32 MJD31C, MJD32C	V _{CEO}	40 100	Vdc
Collector-Base Voltage MJD31, MJD32 MJD31C, MJD32C	V _{CB}	40 100	Vdc
Emitter-Base Voltage	V_{EB}	5.0	Vdc
Collector Current - Continuous	I _C	3.0	Adc
Collector Current - Peak	I _{CM}	5.0	Adc
Base Current	Ι _Β	1.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.12	W W/°C
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	- 65 to + 150	°C
ESD - Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.3	°C/W
Thermal Resistance, Junction-to-Ambient*	$R_{\theta JA}$	80	°C/W
Lead Temperature for Soldering Purposes	TL	260	°C

^{*}These ratings are applicable when surface mounted on the minimum pad sizes recommended.

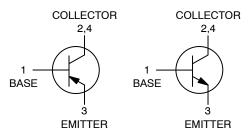


ON Semiconductor®

www.onsemi.com

SILICON POWER TRANSISTORS 3 AMPERES 40 AND 100 VOLTS 15 WATTS

COMPLEMENTARY





DPAK CASE 369C STYLE 1

MARKING DIAGRAM



A = Site Code
Y = Year
WW = Work Week
xx = 1C or 2C
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				1
Collector–Emitter Sustaining Voltage (Note 1) (I _C = 30 mAdc, I _B = 0) MJD31, MJD32 MJD31C, MJD32C	V _{CEO(sus)}	40 100	- -	Vdc
Collector Cutoff Current (V _{CE} = 40 Vdc, I _B = 0) MJD31, MJD32 (V _{CE} = 60 Vdc, I _B = 0) MJD31C, MJD32C	I _{CEO}	-	50 50	μAdc
Collector Cutoff Current (V _{CE} = Rated V _{CEO} , V _{EB} = 0)	ICES	-	20	μAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	1	mAdc
ON CHARACTERISTICS (Note 1)	·			
DC Current Gain $ (I_C = 1 \text{ Adc, } V_{CE} = 4 \text{ Vdc)} $ $ (I_C = 3 \text{ Adc, } V_{CE} = 4 \text{ Vdc)} $	h _{FE}	25 10	- 50	
Collector–Emitter Saturation Voltage (I _C = 3 Adc, I _B = 375 mAdc)	V _{CE(sat)}	-	1.2	Vdc
Base-Emitter On Voltage (I _C = 3 Adc, V _{CE} = 4 Vdc)	V _{BE(on)}	-	1.8	Vdc
DYNAMIC CHARACTERISTICS	·			•
Current Gain – Bandwidth Product (Note 2) (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1 MHz)	f _T	3	-	MHz
Small-Signal Current Gain (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1 kHz)	h _{fe}	20	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

2. $f_T = |h_{fe}| \bullet f_{test}$.

TYPICAL CHARACTERISTICS

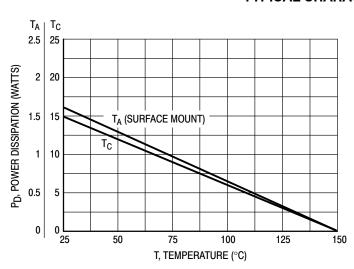
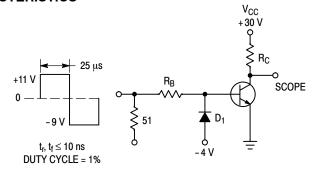


Figure 1. Power Derating



 R_B and R_C VARIED TO OBTAIN DESIRED CURRENT LEVELS D_1 MUST BE FAST RECOVERY TYPE, e.g.: $1N5825 \ USED \ ABOVE \ I_B \approx 100 \ mA$ MSD6100 USED BELOW $I_B \approx 100 \ mA$ REVERSE ALL POLARITIES FOR PNP.

Figure 2. Switching Time Test Circuit

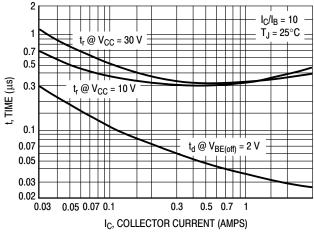


Figure 3. Turn-On Time

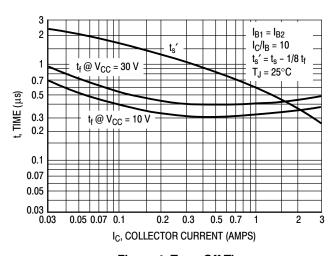


Figure 4. Turn-Off Time

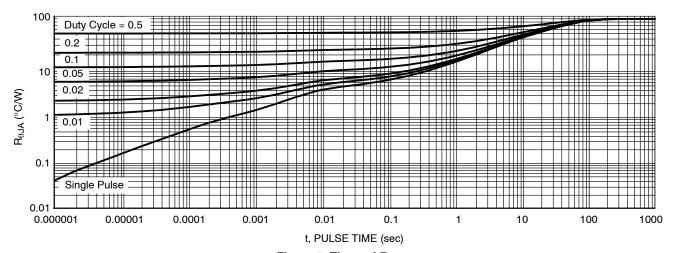
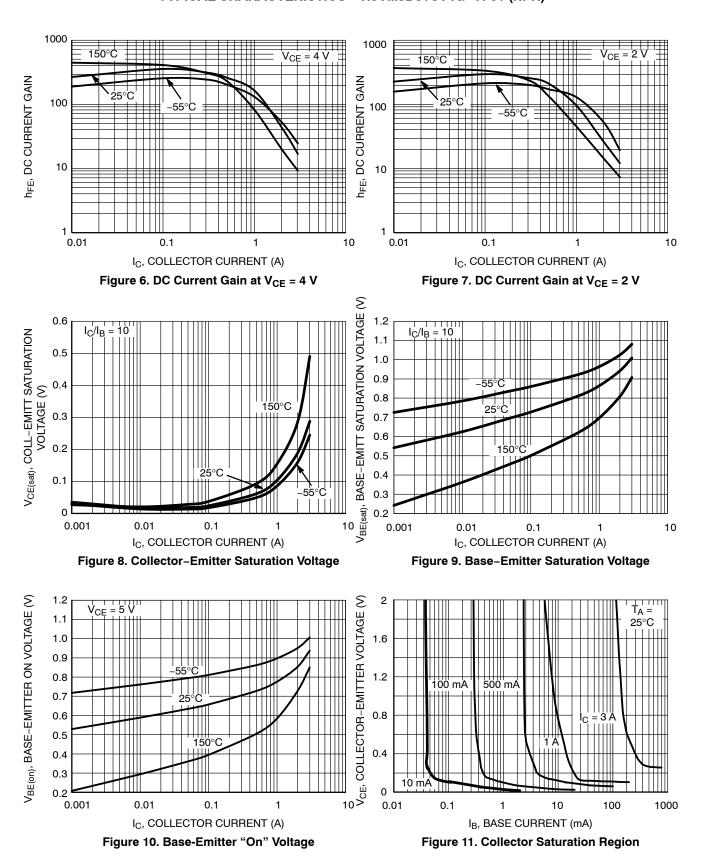


Figure 5. Thermal Response

TYPICAL CHARACTERISTICS - NJVMJD31CT4G-VF01 (NPN)



TYPICAL CHARACTERISTICS - NJVMJD31CT4G-VF01 (NPN)

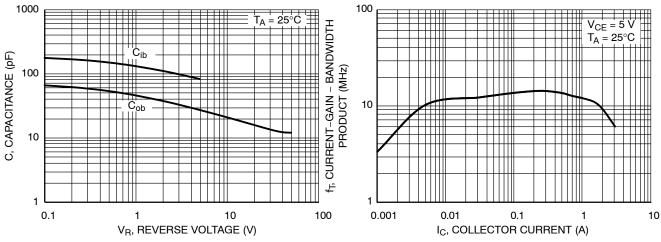
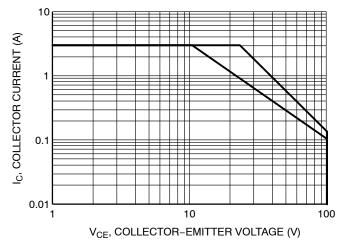
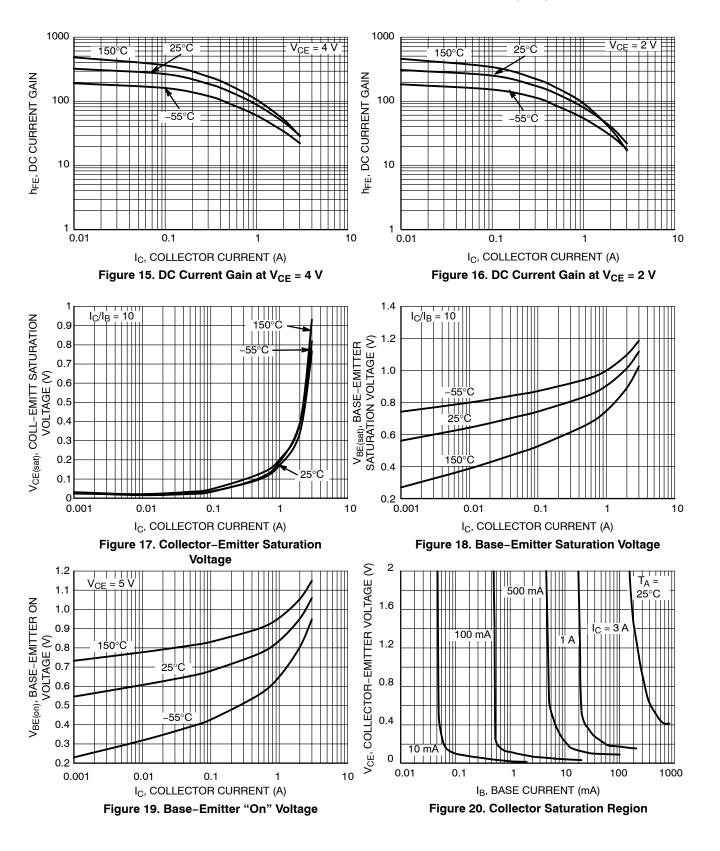


Figure 12. Capacitance

Figure 13. Current-Gain-Bandwidth Product



TYPICAL CHARACTERISTICS - NJVMJD32CT4G-VF01 (PNP)



TYPICAL CHARACTERISTICS - NJVMJD32CT4G-VF01 (PNP)

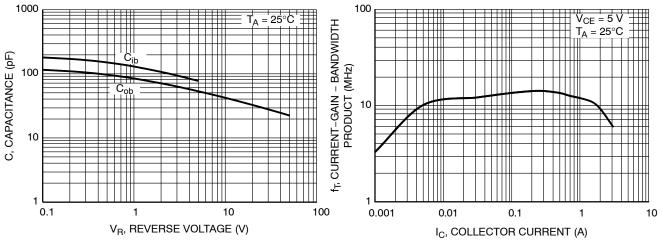


Figure 21. Capacitance

Figure 22. Current-Gain-Bandwidth Product

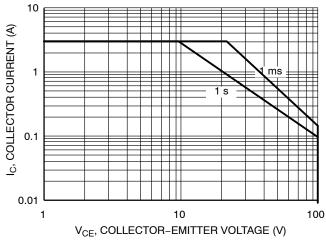


Figure 23. Safe Operating Area

ORDERING INFORMATION

Device	Package Type	Package	Shipping [†]
NJVMJD31CT4G-VF01*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD32CT4G-VF01*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel

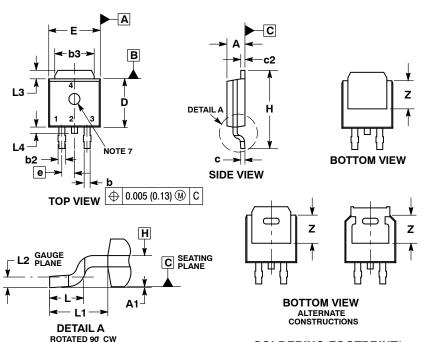
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F



NOTES

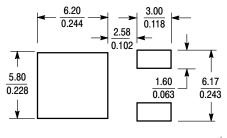
- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- MENSIONS D. AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

STYLE 1:

- PIN 1. BASE 2. COLLECTOR
- - EMITTER COLLECTOR

SOLDERING FOOTPRINT*



SCALE 3:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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